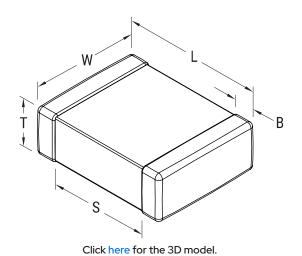


## C1206X331FBGACTU

Aliases (C1206X331FBGAC7800) SMD Comm COG HV Flex, Ceramic, 330 pF, 1%, 630 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra- Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	1mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

S	1.5mm MIN	Dielectri
В	0.6mm +/-0.25mm	Tempera
		Temp. C
Packaging Specifications		Capacita
Packaging	T&R, 180mm, Plastic Tape	Reference Applied
Packaging Quantity	2500	Dissipati

S ::: ::	
Specifications	
Capacitance	330 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	1%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 10/29/2025 © 2006 - 2025 YAGEO